Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.						This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1					Form Type * Distribute										
Supplier	· Information														
Company	name*		Company un	ique ID		Uni	ique ID Autho	rity			Respons	e Date*			
onsemi											2024-05-	2024-05-05			
Contact Name			Title - Contact			Pho	Phone - Contact*				Email - 0	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*				
Product-E	Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name			Ef	ffective Date	Version	Ma	Manufacturing Site		Weight*	UOM	Unit Type	
	LB11620		GP-TE-L-H 3PH PRE SENSOR OPEN; Three pl driver with hall sensor method (open speed control)				024-05-05		PH	РНМ		20.0	mg	Each	
Manufa	cturing Proccess Informatio	n					_								
5 ,			Terminal Base Alloy J-STD-0		J-STD-020 MSL Ratin	ng	Peak Proces	s Body Temperature Max Time at Peak		Temperature Number of R		of Reflow Cycle	es		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		TU Alloy 1		1		260			30 seco		econds 3				
Comments															
level 1 - m	aximum time at peak temperature	during sol	ldering is 10-3	0 seconds											
For more i	information regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Condition											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.19	mg	Supplier	Silicon (Si)	7440-21-3		4.159	mg
			Supplier	Polyimide	Proprietary Data		0.031	mg
Die Attach	0.16	mg	Supplier	Epoxy resins	129915-35-1		0.116	mg
			Supplier	Acrylic resins	Proprietary Data		0.044	mg
Mold Compound-Black	11.05	mg		Epoxy Phenol Resin	proprietary data		1.2155	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0221	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		9.3704	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.442	mg
Substrate and Solder Mask	4.4	mg	В	Nickel (Ni)	7440-02-0		0.3164	mg
			Supplier	Gold (Au)	7440-57-5		0.0682	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		2.6893	mg
			Supplier	Copper (Cu)	7440-50-8		1.3262	mg
Wire Bond - Au	0.2	mg	Supplier	Gold (Au)	7440-57-5		0.2	mg